

# ARTEMIS

## On the road to ECSEL



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Advanced Research & Technology for Embedded Intelligence and Systems

# First Important Things to Know



- **ARTEMIS (and ENIAC) JU** are **INNOVATION** oriented, public-funded RD&I programmes
  - Market-facing developments (higher TRL) ...
  - ... drawing on new basic technologies (lower TRL) that serve these needs
- So: **“INDUSTRY”** refers to the eco-systems of:
  - Large, Medium and Small Enterprises
  - Private / Public Research Organisations
  - Universities
- **Eco-Systems create the critical mass needed for sustainable businesses!**

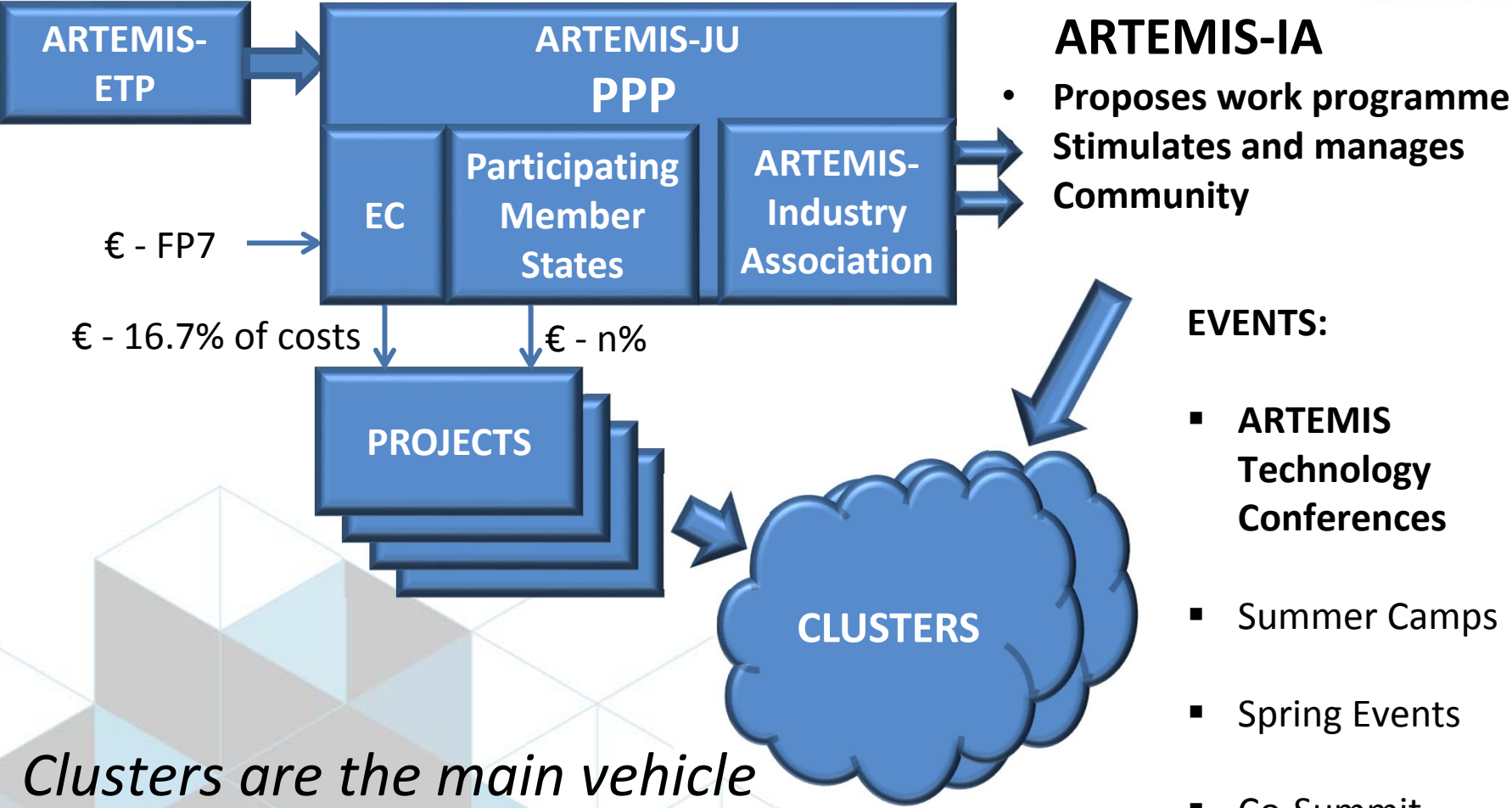
# ARTEMIS JU Research:

## The guiding principles



- **“Think BIG”**
  - = projects with appropriate critical mass and significant societal impact
- **“Act Socio-Economic”**
  - = improved industrial efficiency **“... to strengthen European competitiveness and allow the emergence of new markets and societal applications.”**
    - i.e. a focus on key technical issues, solving high-visibility issues with **commercially valorisable results**
- **“Act Multi-national” (= “Act Pan-European”)**
  - = considers national/regional strategic priorities
- **“Think Different”**
  - = significant and complementary added-value to existing programmes

# Creating Impact – the “PPP model”



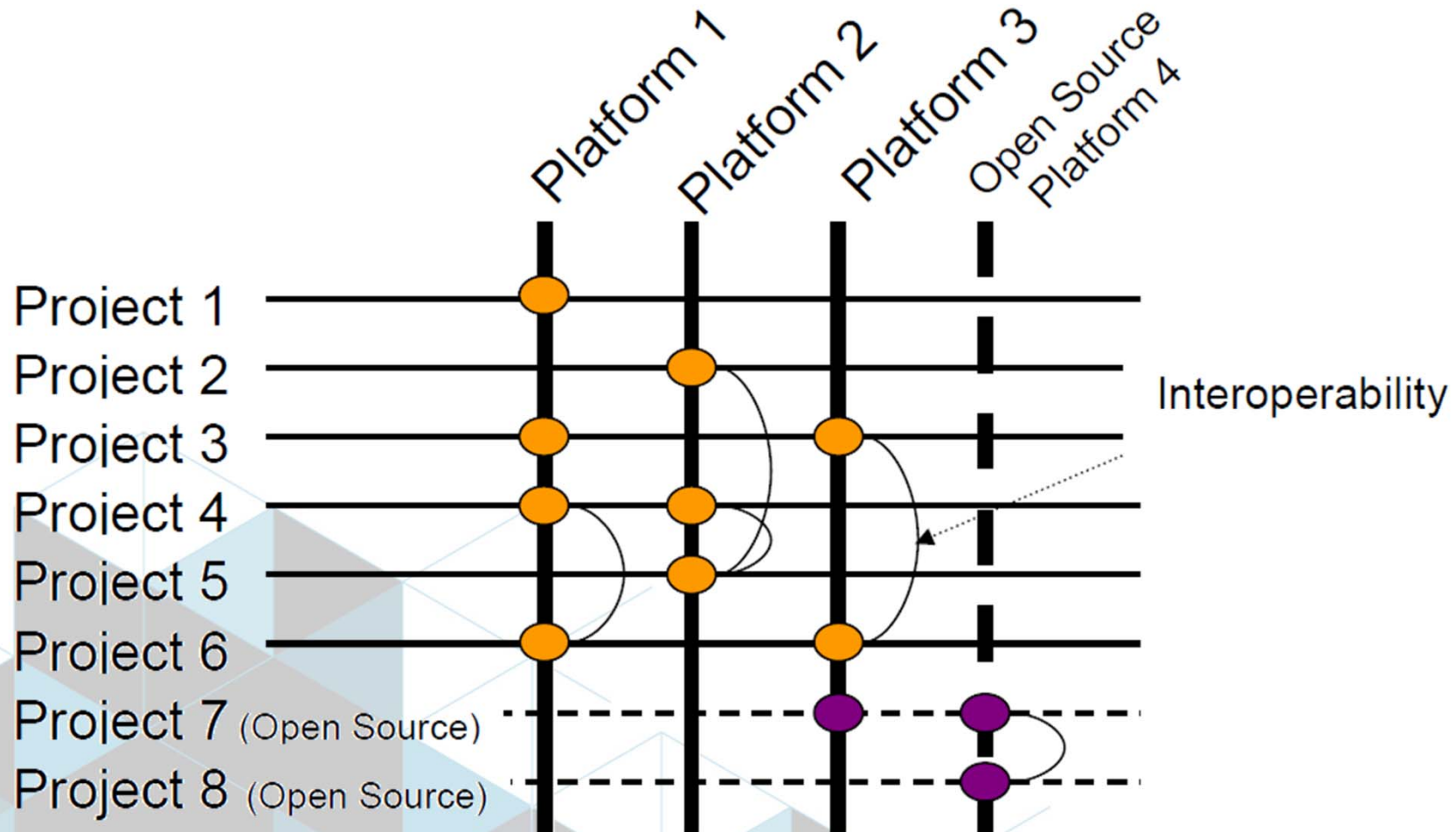
*Clusters are the main vehicle for creating CRITICAL MASS*

# ARTEMIS Tool Platforms



- “Embedded” = tools
- Tools = interoperability !
  - Libraries and design artefacts
- Complex methodologies require special tooling too!
  - Design, V&V, Safety, Certification, ...
- ARTEMIS “Tool Platforms” offers a way to assure integration of heterogenous tooling into a stable, reliable workflow.

# ARTEMIS “Tool Platform” concept

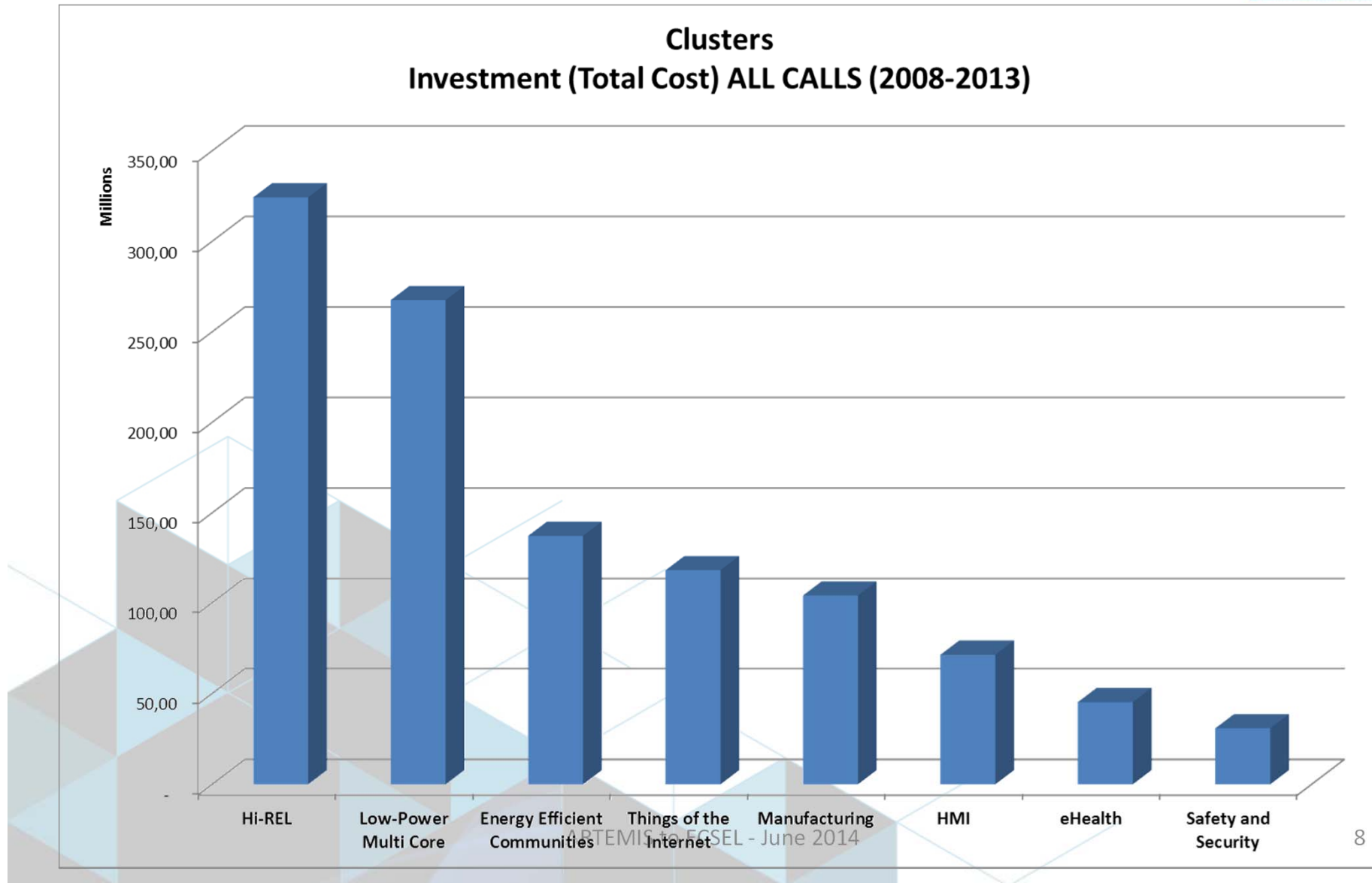


# ARTEMIS projects on Hi-Rel and LPMC



"Hi-Rel"		Low-Power Multi-Core	
Call	Project	Call	Project
2008	CESAR	2008	INDEXYS
2008	CHARTER	2008	SCALOPES
2008	CHESS	2009	ACROSS
2008	SYSMODEL	2009	ASAM
2009	iFEST	2009	SMECY
2009	RECOMP	2010	PRESTO
2010	MBAT	2011	CRAFTERS
2010	pSAFECER	2011	PaPP
2011	DESERVE	2012	CONCERTO
2011	nSafeCer	2012	COPCAMS
2011	VARIES	2013	Almarvi
2011	VeTeSS	2013	EMC2
2012	CRYSTAL	2013	R5-COP

# ARTEMIS programme, as CLUSTERS



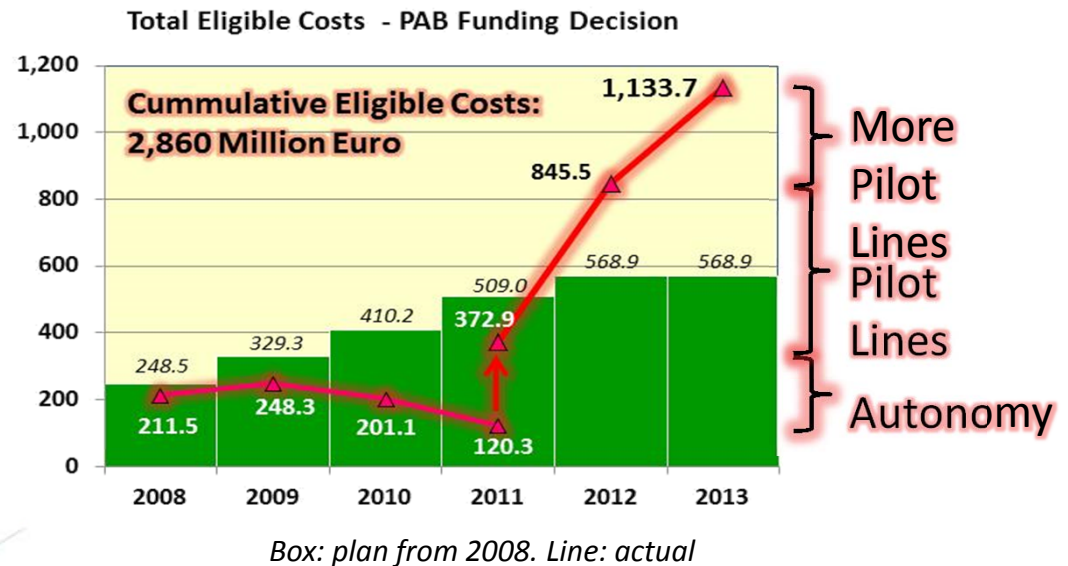


# Game Changer ...



- 2011 - ENIAC JU introduces “Pilot Lines”
  - Very large initiatives leveraging considerable National interest and funding

– *Very successful!*



- 2012 - ARTEMIS introduces “AIPPs”
  - Also very large iniaitves, designed to focus the Innovation Potential of its CLUSTERS

# ARTEMIS AIPPs



- **CRYSTAL**



- Methods and Tools for ultra-high-dependability systems
- Transport, Medical, ...

- **Arrowhead**



- Efficient manufacturing and energy
- Integrated energy distribution for industry and domestic

- **EMC<sup>2</sup>**

- Pushing the boundaries for multi-core programming and use in demanding, mixed-criticality apps.



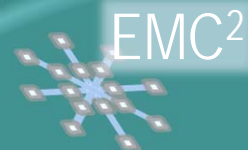
- *Dependable, safe wireless communication -> ASP*
- *eHealth*

# ARTEMIS AIPP "EMC<sup>2</sup>" – the power of clustering

**A CLUSTER of ARTEMIS projects**

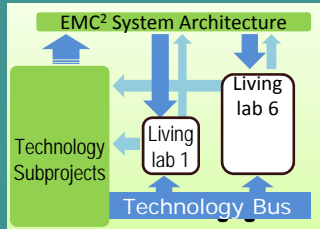
**Multi-core Technology**

- INDEXYS 6
- SCALOPES 4
- iLAND 1
- ACROSS 8
- ASAM 2
- SMECY 6
- PRESTO 2
- CRAFTERS 3
- PaPP 2
- COPCAMS 4
- R3COP 7



**'Embedded Multi-Core Systems for Mixed Criticality Applications in Dynamic and Changeable Real-time Environments'**

**98** Partner, 16 EU Countries, 100 Mio € Budget



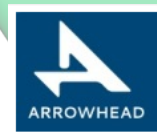
- 10 CESAR
- 2 CHARTER
- 4 CHES
- 1 SYSMODEL
- 6 iFEST
- 6 RECOMP
- 11 MBAT
- 4 pSafeCer
- 5 nSafeCer

**Safety-critical Systems**

**Another CLUSTER of ARTEMIS projects**

- 1 VARIES
- 7 VeTeSS
- 4 CONCERTO

**Innovation Pilots**



**And 2 AIPPs!**

**Scientific Communities**



Number 1:  
ARTEMIS has been the largest programme ever, focused on Safety Critical Systems

Number 2:  
ARTEMIS has been the largest programme ever, focused on Multi-core Technology

.. starting from single projects towards the EMC<sup>2</sup> platform approach..

# What does this mean for ECSEL?

- **ECSEL** = “Electronic Components and Systems”
  - Nanoscale semiconductor technology
    - (ENIAC-JU) – high-performance computing devices and more
  - Smart interfaces and integration
    - (EPoSS ETP) – interface to the physical world
  - System Engineering, software architecture and model-based design
    - (ARTEMIS-JU) – adding application value, especially for complex, high-dependability systems



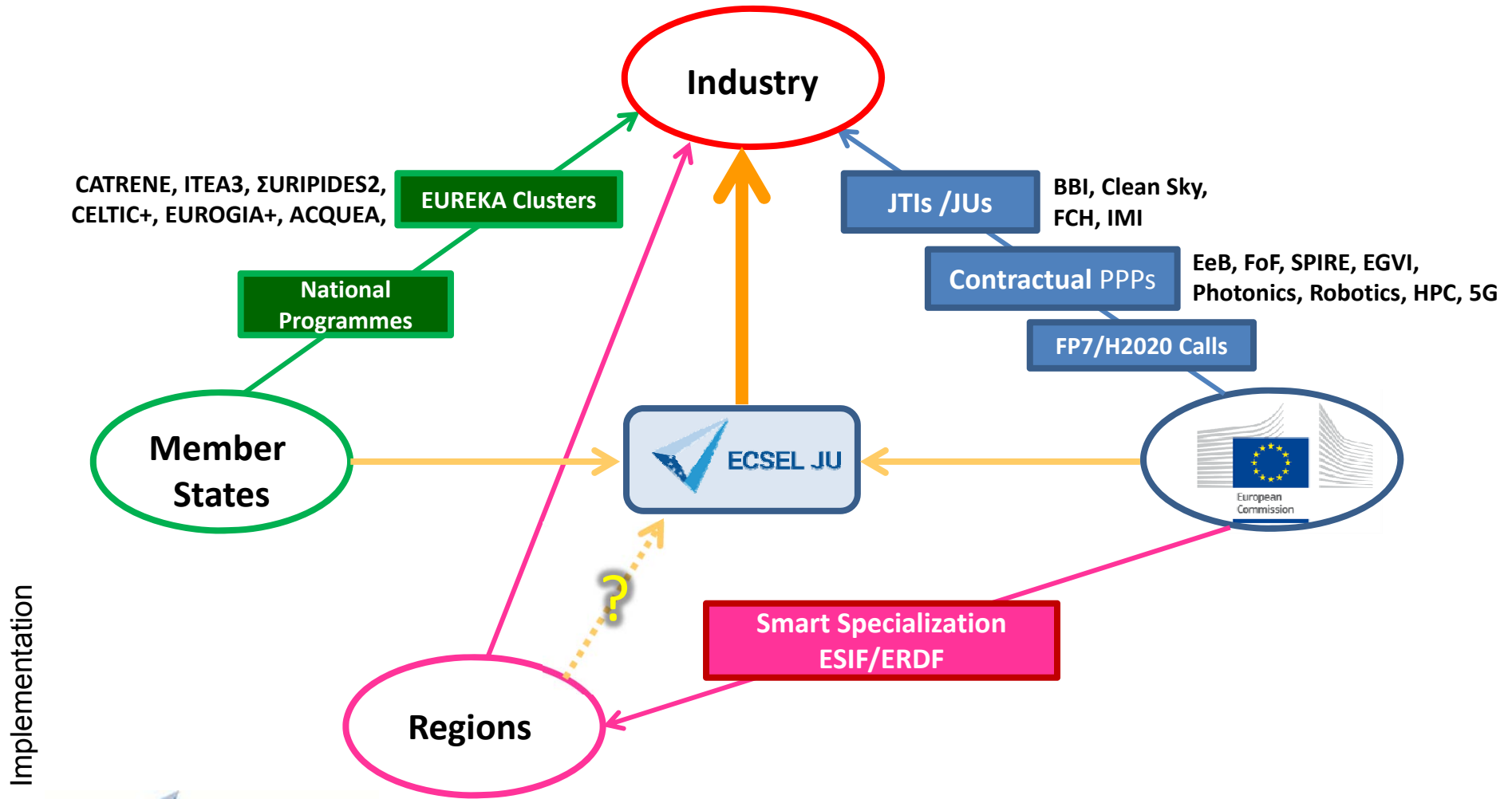
# What does this mean for ECSEL?

## ECSEL = Scale and Impact

- Both ENIAC-JU and ARTEMIS have proven that large, “Pilot Line”- like initiatives are:
  - Feasible
    - we have good project managers !
  - Effective
    - high-visibility results of direct industrial/societal relevance
  - Economic
    - A High ROI for the public and private investments
  - **“Pilot Lines” are AN ESSENTIAL COMPLEMENT to European collaborative R&D projects**



# The Tripartite Joint Undertaking: one Mechanism among Many



# Draft Multi-Annual Strategic Plan for ECSEL



**ECSEL JU**

# Programme Areas

- ECSEL is called upon to address:
  - a) design technologies, process and integration, equipment, materials and manufacturing for micro- and nanoelectronics while targeting miniaturisation, diversification and differentiation, heterogeneous integration;*
  - b) processes, methods, tools and platforms, reference designs and architectures, for software and/or control-intensive embedded/cyber-physical systems, addressing seamless connectivity and interoperability, functional safety, high availability, and security for professional and consumer type applications, and connected services; and*
  - c) multi-disciplinary approaches for smart systems, supported by developments in holistic design and advanced manufacturing to realise self-reliant and adaptable smart systems having sophisticated interfaces and offering complex functionalities based on, for example, the seamless integration of sensing, actuating, processing, energy provision and networking.*



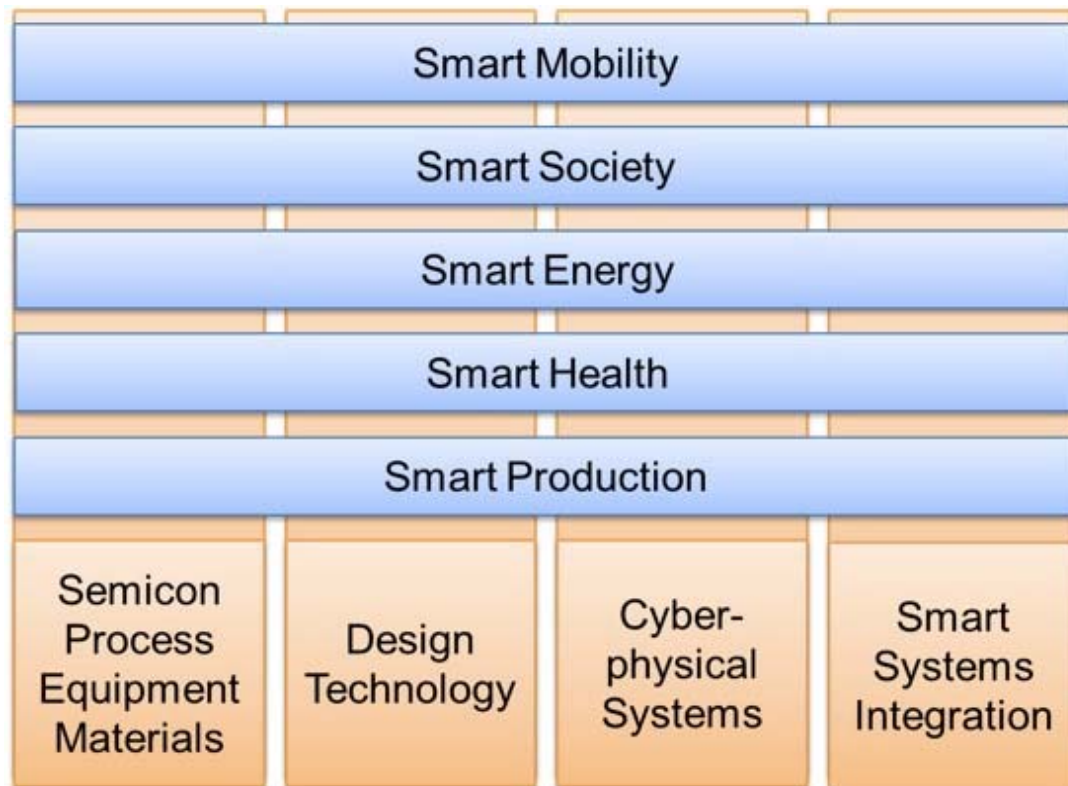


# The ECSEL JU Programme

- Based on the “Multi-Annual Strategic Research and Innovation Agenda” (**MASRIA**) published by the participating Industry Associations
  - Available on their respective web-sites
  - (Search for: ARTEMIS-IA, AENEAS, EPoSS)
- Covers the complete electronics components and systems value chain through key applications and enabling technologies (including the necessary design technologies)
  - Semiconductor technologies and devices
  - Smart sensors / actuators
  - Embedded intelligence and software / **Cyber Physical Systems (CPS)**
  - Design technologies



# ECSEL JU Draft Programme Architecture



*Applications driven by the opportunities created for Industry to help address Societal Challenges*

Key Applications

**PART A**

**PART B**  
Essential Capabilities

*Technologies needed by Industry to make it happen...*



# Part A – Key Applications

## 1. Smart mobility

- improve air quality, reduce congestion, sustain mobility for the elder generation and excel towards accident free mobility

## 2. Smart society

- Intelligent, secure and easy-to-use solutions for digital inclusion, guaranteeing citizen privacy and reaching broad acceptance in the public.

# Part A – Key Applications

## 3. Smart energy

- Sustainable energy generation and conversion, Reducing energy consumption, Efficient community energy management

## 4. Smart health

- Support for affordable care and well-being at home, abroad and in hospitals; heuristic care; food processing; and food safety



# Part A – Key Applications

## 5. Smart production

- I. manufacturing and process automation and new manufacturing and process technologies enabled by advanced electronics systems.
- II. manufacturing of semiconductors as a special topic



# Part B – Essential Capabilities

## 1. Semiconductor Process, Equipment, and Materials

- leadership in processing know-how for:
  - advanced and beyond CMOS (More Moore, MM),
  - heterogeneous (More than Moore, MtM)
  - and System in Package (SiP) technology

## 2. Design technologies

- *“transform ideas and requirements efficiently into innovative, manufacturable, and testable products, at whatever level in the value chain”*



# Part B – Essential Capabilities

## 3. Cyber-physical systems

- *“next generation embedded intelligent ICT systems that are interconnected, interdependent, collaborative, autonomous and provide computing and communication, monitoring/control of physical components/processes”*

## 4. Smart systems integration

- *“SSI addresses the (electronic) system itself, enabled by heterogeneous 3D integration of new building blocks for sensing, data processing, actuating, networking, energy scavenging and managing, that combine nano-, micro-, and power-electronics with micro-electro-mechanical and other physical, electromagnetic, chemical, and biological principles”*



# Project Topics

- ***“Projects of the ECSEL programme do not necessarily have to limit themselves to covering only one of these key applications or essential technology capabilities; on the contrary, multi/cross-capability projects will be encouraged wherever relevant. This cross-capability work is vital in creating initiatives of adequate critical mass and vital in fostering innovation ...”***





# The ECSEL JU Programme

- Based on Calls for Proposals
  - At least one per year
- Includes:
  - Pilot Lines and Innovation Pilots
    - large-scale integrating projects
    - specifically include higher TRLs
  - R&D projects
    - that should not work in isolation !
    - typically addressing lower TRLs



# Project Types

- Innovation Actions
  - Pilot Lines and test beds
  - Demonstrators, innovation pilot projects and zones of full-scale testing
  - Higher TRLs – 4 to 8
- Research and Innovation Actions
  - Research and development (“Standard”) projects
  - TRL 2 to 5

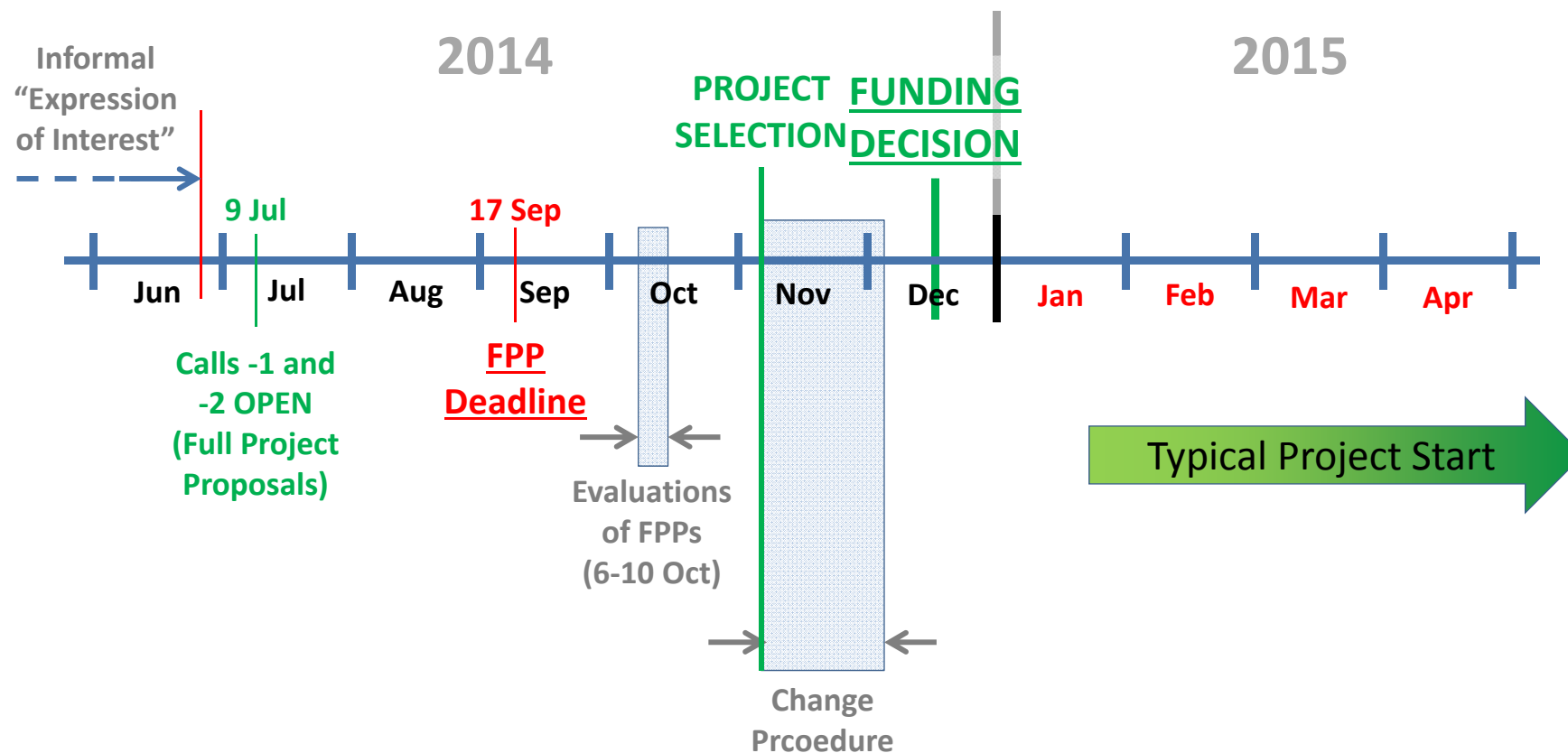


# Calls in 2014

- 2 Calls
  - Research Innovation Action (RIA)
  - Innovation Action (IA)

Call	Type	Type equivalence	TRL focus
ECSEL 2014-1	Research and Innovation Action (RIA)	Industrial/Applied Research projects	2-5
ECSEL 2014-2	Innovation Action (IA)	Experimental development projects	4-8

# Calls 2014 - Timeline



# Conclusions

- ARTEMIS and ENIAC have set the scene
  - PPP model with tri-partite funding
  - Market-facing programmes supporting major initiatives
- ECSEL JU is ready to take over
  - Call mechanisms in place
  - A rich strategic plan that will encourage **impactful projects and pilots** in a programme embracing the whole ECS value-chain.





# THANK YOU

